

Wavin

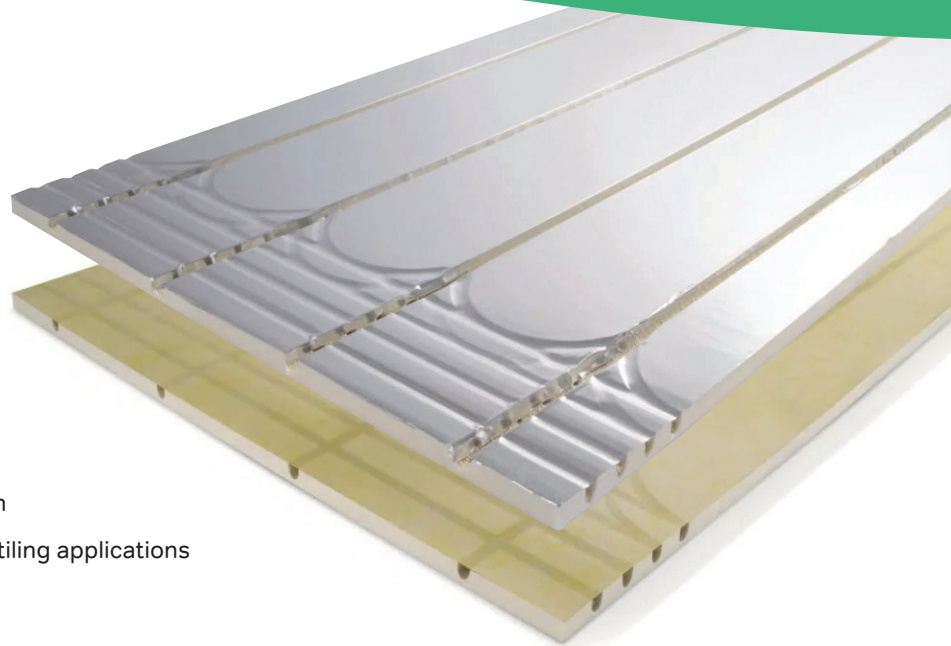
Lowbuild Foil & Glass Fibre Mesh Faced Board

Product Information

Wavin Lowbuild low profile routed underfloor heating insulation boards have an ultra high compressive strength and aluminium foil facing for added thermal diffusion. They provide an effective solution to limited height underfloor heating application.

Product Benefits

- Low profile, 18mm panel
- Aluminium foil facing for improved heat diffusion
- Glass fibre mesh facing also available for direct tiling applications
- Ultra high compressive strength – 500kPa
- Easy to cut to size and install



Technical Data		Wavin Lowbuild
Product description	–	Low profile, ultra high compressive strength UFH board
Strength at 10% compression	kPa	500
Thermal conductivity	W/mK	0.035
Temperature range	°C	-50/+75
Route sizes available (to suit pipe diameter)	mm	12
Pipe centres	mm	150
Board size	mm	600 x 1200
Thickness	mm	18

Third Party Accreditation and Approvals



Environmental Credentials

